

SBC-3.5-MX8M-Mini

3.5" SBC with NXP i.MX 8M Mini Processors

Heterogeneous multi-core processing architecture for edge node computing and multimedia





HIGHLIGHTS

NXP i.MX 8M Mini Family

GC320 2D accelerator +

GCNanoUltra 3D accelerator



CONNECTIVITY

Up to 2x GbE; opt Wifi; up to 2x RS-232 or RS-485 or CAN; opt LTE Cat4 Modern with SIM slot or eSIM



MEMORY

Soldered on-board LPDDR4-3000 memory, up to 4GB







MAIN FIELDS OF APPLICATION



Smart Devices

FEATURES			
	NXP i.MX 8M Mini Family based on Arm® Cortex®-A53 cores + general purpose Cortex®-M4 400MHz processor: i.MX 8M Mini Quad - Full featured, 4x Cortex®-A53 cores up to 1.8GHz i.MX 8M Mini Dual - Full featured, 2x Cortex®-A53 cores up to 1.8GHz i.MX 8M Mini Solo - Full featured, 1x Cortex®-A53 cores up to 1.8GHz i.MX 8M Mini Solo - Full featured, 1x Cortex®-A53 cores up to 1.8GHz i.MX 8M Mini Quad Lite -4x Cortex®-A53 cores up to 1.8GHz, no VPU i.MX 8M Mini Dual Lite -2x Cortex®-A53 cores up to 1.8GHz, no VPU i.MX 8M Mini Solo Lite -1x Cortex®-A53 cores up to 1.8GHz, no VPU	문 Networking	2x GbEthernet interfaces (1 optional) Optional shielded ultra-small dual Band WiFi 802.11 a/b/g/n/ ac with BT 5.0 module onboard Optional soldered on-board LTE Cat 4 Modem with microSIM slot or Telenor eSIM with 5MB Bundle
Processor		• < USB	2x USB 2.0 Host ports on Type-A socket 2x USB 2.0 Host ports on internal pin header 1x USB Host or client port on micro-AB connector (interface shared with the optional on-board modem)
		Audio	Digital Mic In connector (2x PDM inputs) Amplified mono Speaker Output
Max Cores		Serial Ports	Up to 2x RS-232 or RS-485 or CAN Serial ports (factory options, shared with GPIOs and SPI interfaces) 2x Debug UARTS
Memory Memory	Soldered-down LPDDR4 memory, up to 4GB total, 32-bit interface		I/O Connectors with:
Graphics	GC320 2D accelerator + GCNanoUltra 3D accelerator Embedded VPU (not for Lite processors), able to offer: VP9, HEVC/H.265, AVC/H.264, VP8 HW Decoding AVC/H.264, VP8 HW encoding OpenGL ES 2.0, OpenVG 1.1 support	Other Interfaces	
Video Interfaces	LVDS Single/Dual Channel connector or eDP connector (factory alternatives) MIPI-CSI Camera interface connector	ctor or eDP connector State of the power RTC (factor options) Watship	
Video Resolution	Up to 1920x1080p60, 24bpp Support Onboard Buzzer (Comm. temp. range of		
Mass Storage	Optional eMMC 5.1 drive on-board, up to 64GB MicroSD slot 2Kb I2C Flash QSPI Flash	Power Supply	+12V _{DC} ÷ +24V _{DC}

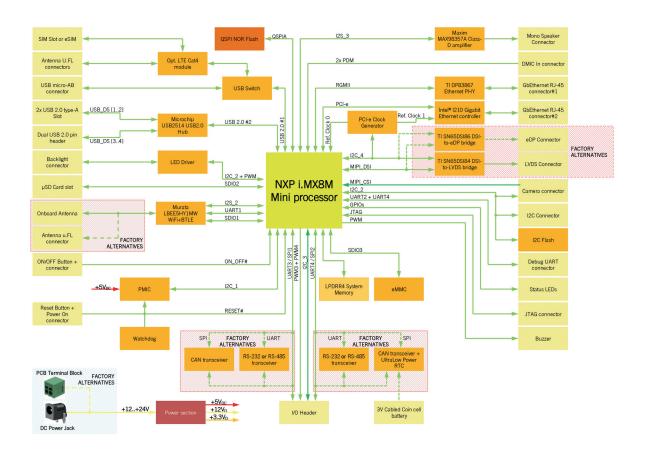


FEATURES

<u> </u>				
	OS	Operating System	Yocto Android (planned)	
	<u>[]</u>	Operating Temperature*	0°C \div +60°C (Commercial version) -40°C \div +85°C (industrial version, limited to -30°C \div +85°C with WiFi/BT module on-board)	
	L	Dimensions	146x102 mm (3.5" form factor)	

*Measured at any point of SECO standard heatsink for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.

BLOCK DIAGRAM





Streamline and expedite your edge computing implementations

EDGEHOG OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust Al-based protection.

DATA ORCHESTRATION

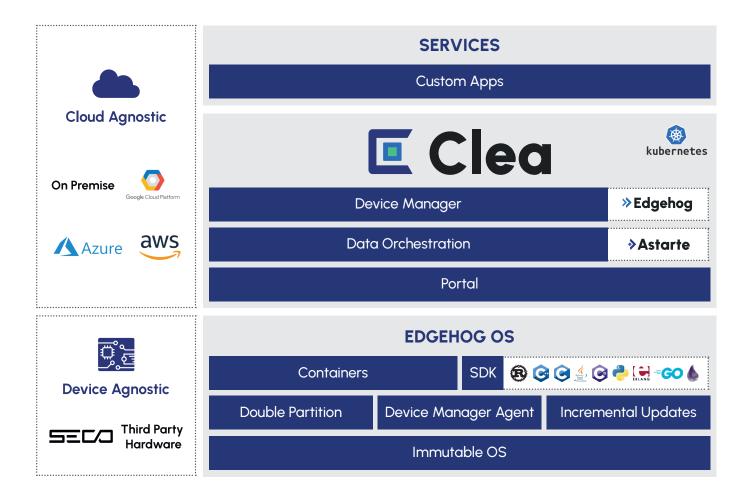
Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI.

DEVICE MANAGER

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

PORTAL

Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.



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EDGEHOG OS



CLEA DOCS



